



Click [here](#) for the 3D model.

### Dimensions

|           |                  |
|-----------|------------------|
| Chip Size | 1206             |
| L         | 3.2mm +/-0.2mm   |
| W         | 1.6mm +/-0.2mm   |
| T         | 0.78mm +/-0.10mm |
| B         | 0.5mm +/-0.25mm  |

### Packaging Specifications

|                    |                          |
|--------------------|--------------------------|
| Packaging          | T&R, 180mm, Plastic Tape |
| Packaging Quantity | 4000                     |

### General Information

|                  |   |
|------------------|---|
| Series           | SMD Auto X8R HT150C   |
| Style            | SMD Chip  |
| Description      | SMD, MLCC, High Temperature, Ultra-Stable, Automotive Grade |
| Features         | High Temperature, Ultra-Stable, Automotive Grade            |
| RoHS             | Yes   |
| Termination      | Tin   |
| Marking          | No  |
| Qualifications   | AEC-Q200  |
| AEC-Q200         | Yes   |
| Component Weight | 17 mg   |
| Shelf Life       | 78 Weeks  |
| MSL              | 1   |

### Specifications

|  |   |
|--|---|
| Capacitance  | 15 pF   |
| Measurement Condition  | 1 MHz 1.0Vrms                                   |
| Capacitance Tolerance  | 1%  |
| Voltage DC   | 100 VDC   |
| Dielectric Withstanding Voltage                                    | 250 VDC   |
| Temperature Range  | -55/+150°C                                      |
| Temperature Coefficient  | X8R   |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 15%, 1MegaHz 1.0Vrms                            |
| Dissipation Factor   | 2.5% 1 MHz 1.0Vrms                              |
| Aging Rate   | 0% Loss/Decade Hour: Referee Time is 1000 Hours |
| Insulation Resistance  | 100 GOhms                                       |